

DIO59015 USB-Compliant Single-cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Features

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Faster Charging than Linear
- Charge Voltage Accuracy: 0.5% at 25°C 1% from 0 to 125°C
- ±7% Input Current Regulation Accuracy
- ±7% Charge Current Regulation Accuracy
- 26V Absolute Maximum Input Voltage
- 6V Maximum Input Operating Voltage
- 1.5A Maximum Charge Rate
- Programmable through High-Speed I²C Interface(3.4Mb/s) with Fast Mode Plus Compatibility
 - Input Current
 - Fast-Charge/Termination Current
 - Charger Voltage
 - Recharge Voltage
 - Termination Enable
- 2MHz Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint 1µH External Inductor
- 1.8V Regulated Output from VBUS for Auxiliary Circuits
- Dynamic Input Voltage Control
- Low Reverse Leakage to Prevent Battery
 Drain to VBUS
- 5V, 600mA Boost Mode for USB OTG for 3.2V to 4.5V Battery Input
- Available in TQFN3*3-16, DFN3*3-12 Packages.

Descriptions

The DIO59015 combines a highly integrated switch-mode charger, to minimize single-cell Lithium-ion (Li-ion) charging time from a USB power source, and a boost regulator to power a USB peripheral from the battery.

The charging parameters and operating modes are programmable through an I^2C Interface that operates up to 3.4Mbps. The charger and boost regulator circuits switch at 2MHz to minimize the size of external passive components.

The DIO59015 provides battery charging in three phases: conditioning, constant current and constant voltage.

To ensure USB compliance and minimize charging time, the input current limit can be changed through the I²C by the host processor. Charge termination is determined by a programmable minimum current level.

The integrated circuit (IC) automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode, preventing leakage from the battery to the input. Charge current is reduced when the die temperature reaches 120°C, protecting the device and PCB from damage.

The DIO59015 can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery and uses the same external components used for charging the battery.

Applications

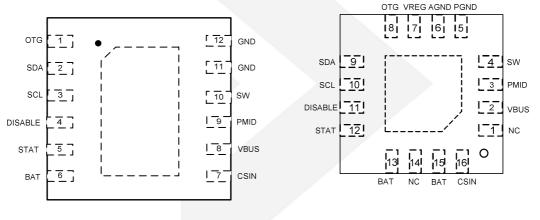
- Cell Phones, Smart Phones, PDAs
- Tablet, Portable Media Players
- Gaming Device, Digital Cameras



Ordering Information

Order Part Number	Top Marking		T _A	Package	
DIO59015CL16	59015	Green	-40 to +85°C	TQFN-16	Tape & Reel, 5000
DIO59015CD12	59015	Green	-40 to +85°C	DFN3*3-12	Tape & Reel, 5000

Pin Assignments



DFN3*3-12

TQFN3*3-16







Pin Definitions

Name	Description
VBUS	Charger Input Voltage and USB-OTG output voltage. Bypass with a 1µF capacitor to PGND.
NC	No Connect. No external connection is made between this pin and the IC's internal circuitry.
SCL	I ² C Interface Serial Clock. This pin should not be left floating.
PMID	Power Input Voltage. Power input to the charger regulator, bypass point for the input current sense, and high-voltage input switch. Bypass with a minimum of 10μ F, 6.3V capacitor to PGND.
SDA	I ² C Interface Serial Data. This pin should not be left floating.
SW	Switching Node. Connect to output inductor.
STAT	Status. Open-drain output indicating charge status. The IC pulls this pin LOW when charging.
PGND	Power Ground. Power return for gate drive and power transistors. The connection from this pin to the bottom of CMID should be as short as possible.
OTG	On-The-Go. Enables boost regulator in conjunction with OTG_EN and OTG_PL bits (see Table 14).
CSIN	Charging current detection input terminal.
DISABLE	Charge Disable. If this pin is HIGH, charging is disabled. When LOW, charging is controlled by the I ² C registers.
VREG	Regulator Output. Connect to a 1μ F capacitor to PGND. This pin can supply up to 2mA of DC load current. The output voltage is PMID, which is limited to 1.8V.
ВАТ	Battery Voltage. Connect to the positive (+) terminal of the battery pack. Bypass with a 0.1μ F capacitor to PGND if the battery is connected through long leads.
GND	Power Ground.
AGND	Analog ground.



Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Rating" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maxim rating conditions for extended periods may affect device reliability.

Parameter		Rating	Unit	
	Continuous	-1.4 to 26.0	V	
VBUS Voltage	Pulsed, 100ms Maximum Non-Repetitive	-2.0 to 26.0	v	
STAT Voltage		-0.3 to 26.0	V	
PMID Voltage		6.5	V	
SW, CSIN, VBAT, DISABLE Voltage		-0.3 to 6.5		
Voltage on Other Pins		-0.3 to 6.5	V	
Maximum V_{BUS} Slope above 5.5	V when Boost or Charger are Active	4	V/µs	
FSD	НВМ	2000	V	
ESD CDM		500	v	
Junction Temperature		-40 to 150	°C	
Storage Temperature		-65 to 150	°C	
Lead Soldering Temperature, 10) Seconds	260	°C	

Recommend Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended Operating conditions are specified to ensure optimal performance to the datasheet specifications. DIOO does not Recommend exceeding them or designing to Absolute Maximum Ratings.

Parameter		Rating	Unit
Supply Voltage		4 to 6	V
Maximum Battery Voltage when Boost enabled		4.5	V
Negative VBUS Slew Rate during VBUS Short	T _A ≤60°C	4)/////
Circuit, C _{MID} ≤10µF	T _A ≥60°C	2	V/µs
Ambient Temperature		-30 to +85	°C
Junction Temperature		-30 to +120	°C



Electrical Characteristics

 $V_{IN} = 5V, T_A = 25^{\circ}C$, unless otherwise specified.

V_{IN} = 5V, T_A = 25°C, unless otherwise specified.						
Symbol	Parameter	Test Conditions	Min	Тур	Мах	Unit
Power Supp	blies					
		V _{BUS} >V _{BUS(min)} , PWM Switching		10		mA
I _{VBUS}	VBUS Current	V _{BUS} > V _{BUS(min}); PWM Enabled, Not Switching (Battery OVP Condition); I_IN Setting=100 mA		0.2		mA
		0°C <tj<85°c, hz_mode="1</td"><td></td><td>88</td><td></td><td>μΑ</td></tj<85°c,>		88		μΑ
I _{LKG}	VBAT to VBUS Leakage Current	0°C <t<sub>J<85°C, HZ_MODE=1, V_{BAT}=4.2V, V_{BUS}=0V</t<sub>		1.6	15.0	μA
I	Battery is charge Current in	0°C <t<sub>J< 85°C, HZ_MODE=1, V_{BAT}=4.2V</t<sub>		5	10	μA
IBAT	High- Impedance Mode	DISABLE=1, 0°C <t<sub>J<85°C, V_{BAT}=4.2V</t<sub>		5	10	μΑ
Charger Vo	Charger Voltage Regulation					
	Charge Voltage Range		4.2		4.4	
V _{OREG}	Charge Vieltage Assures	T _A =25°C	-0.5%		+0.5%	V
	Charge Voltage Accuracy	T _J =0 to 125°C	-1%		+1%	
Charging C	Current Regulation					
	Output Charge Current Range	$V_{SHORT} < V_{BAT} < V_{OREG},$ Rsense=68m Ω	550		1500	mA
I _{OCHRG}	Charge Current Accuracy	$20mV \le V_{IREG} \le 40mV$	-7		7	%
	Across R _{SENSE}	V _{IREG} >40mV	-4		4	%
Logic Leve	IS: DISABLE, SDA, SCL, OTG					
V _{IH}	High-Level Input Voltage		1.05			V
VIL	Low-Level Input Voltage				0.4	V
l _{iN}	Input Bias Current	Input Tied to GND or V _{IN}		0.01	1.00	μA
Charge Ter	mination Detection					
	Termination Current Range	V_{BAT} > V_{OREG} - V_{RCH} , R_{SENSE} =68m Ω	50		400	mA
	Termination Current Accuracy	[V _{CSIN} - V _{BAT}] from 6mV to 20mV	-25		+25	%
I _(TERM)	Termination Current Accuracy	$[V_{CSIN} - V_{BAT}]$ from 20mV to 40mV	-10		+10	%
	Termination Current Deglitch Time			30		ms
1.8V Linear	Regulator					
V _{REG}	1.8V Regulator Output	I _{REG} from 0 to 2mA	1.7	1.8	1.9	V



		DIO59015				
	Short-Circuit Current Limit			4.8		mA
Input Power	Source Detection		4		L	<u></u>
V _{IN(MIN)}	VBUS Input Voltage Rising	To Initiate and Pass VBUS Validation	3.75	4	4.25	V
V _{hys}				0.3		V
tvbus_valid	VBUS Validation Time			30		ms
Special Cha	rger (V _{BUS})					
V _{SP}	Special Charger Set point Accuracy		-3		+3	%
Input Currei	nt Limit					
		REG[7:6]=00	TBD	100	TBD	
	laurat Orana at Linzit Thurson and	REG[7:6]=01	470	500	530	
I _{INLIM}	Input Current Limit Threshold	REG[7:6]=10	750	800	850	mA
		REG[7:6]=11		No limit		
Battery Rec	harge Threshold					
N	Recharge Threshold	Below V _(OREG)	50		200	mV
V _{RCH}	Deglitch Time	V_{BAT} Falling Below V_{RCH} Threshold		30		ms
STAT Outpu	ıt					
V _{STAT(OL)}	STAT Output Low	I _{STAT} =10mA			0.4	V
I _{STAT(OH)}	STAT High Leakage Current	V _{STAT} =5V			1	μA
Sleep Comp	parator					
V _{SLP}	Sleep-Mode Entry Threshold, V_{BUS} - V_{BAT}	$4V \leqslant V_{BAT} \leqslant V_{OREG}$, V_{BUS} Falling	0	0.04	0.1	V
V _{SLP-EXIT}	Sleep-Mode Exit Threshold, V _{BUS} V _{BAT}			0.1		v
t _{SLP_EXIT}	Deglitch Time for VBUS Rising Above V_{BAT} by V_{SLP}	Rising Voltage		30		ms
Power Swite	ches					
	Q3 On Resistance(VBUS to PMID)	I _{IN(LIMIT)} =500mA		86		
R _{DS(ON)}	Q1 On Resistance(PMID to SW)			85		mΩ
	Q2 On Resistance(SW to GND)			75		
Charger PW	/M Modulator					
f _{SW}	Oscillator Frequency		1.7	2	2.3	MHz
D _{MAX}	Maximum Duty Cycle				100	%
D _{MIN}	Minimum Duty Cycle			6		%

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I _{SYNC}	Synchronous to Non-Synchronous Current Cut-Off Threshold ⁽²⁾	Low-Side MOSFET(Q2) Cycle-by- Cycle Current Limit		300		mA
Boost Mode	• Operation(OPA_MODE=1, HZ_M	ODE=0)				
	V _{BOOST} Boost Output Voltage at VBUS	2.5V < V_{BAT} <4.5V, I_{LOAD} from 0 to 200mA	4.88	5.15	5.25	V
VBOOST		$3.0V < V_{BAT} < 4.5V$, I_{LOAD} from 0 to $500mA$	4.85	5.15	5.25	V
I _{BAT(BOOST)}	Boost Mode Quiescent Current	PFM Mode, V _{BAT} =3.6V, I _{OUT} =0		500		μA
ILIMPK(BST)	Q2 Valley Current Limit		1200	1600	2000	mA
	Minimum Battery Voltage for Boost	While Boost Active		2.6		N
UVLO _{BST}	Operation	To Start Boost Regulator		2.7		V
Battery Dete	Battery Detection					
I _{DETECT}	Battery Detection Sink Current ⁽¹⁾	Begins after Charge Termination Detected		-10		mA
t _{DETECT}	Battery Detection Time			30		ms
Protection a	and Timers			L		
	VBUS Over-Voltage Shutdown	V _{BUS} Rising	5.82	6	6.2	V
VBUS _{OVP}	Hysteresis	V _{BUS} Falling		200		mV
ILIMPK(CHG)	Q1 Cycle-by-Cycle Peak Current Limit	Charge Mode		3		А
	Battery Short-Circuit Threshold	V _{BAT} Rising		2		V
V _{SHORT}	Hysteresis	V _{BAT} Falling		100		mV
I _{SHORT}	Linear Charging Current	V _{BAT} <v<sub>SHORT</v<sub>		30		mA
-	Thermal Shutdown Threshold	T _J Rising		145		°C
T _{SHUTDWN}	Hysteresis	TJ Falling		10		Ľ
T _{CF}	Thermal Regulation Threshold	Charge Current Reduction Begins		120		°C
t _{INT}	Detection Interval			30		ms

Notes:

1. Negative current is current flowing from the battery to VBUS (discharging the battery).

2. Q2 always turn on for 60ns, then turns off if current is below $I_{\mbox{\scriptsize SYNC}}.$



I²C Timing Specifications

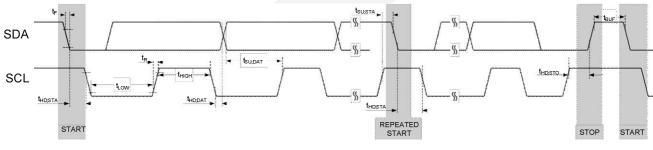
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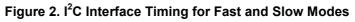
Symbol Parameter Test Conditions Min Typ Max Unit fsct. SCL Clock Frequency Standard Mode 0 100 400	Guaranteed by	Guaranteed by design.						
fsc. SCL Clock Frequency Fast Mode Image: Migh-Speed Mode, Ca<:100pF	Symbol	Parameter	Test Conditions	Min	Тур	Мах	Unit	
			Standard Mode			100		
$ \begin{array}{ c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline & & & & & & & & & & & & & & & & & & $	f	SCI Clock Fraguenay	Fast Mode			400	kU-	
	ISCL	SCL Clock Frequency	High-Speed Mode, $C_B \leq 100 pF$			3400	KHZ	
			High-Speed Mode, $C_B \leqslant 400 pF$			1700		
	+	Bus-Free Time between STOP	Standard Mode		4.7			
	^L BUF	and START Conditions	Fast Mode		1.3		μs	
$ \frac{1}{100 \text{ strain}} + \text{Hold Time} + \frac{\text{Fast Mode}}{\text{High-Speed Mode}} = \frac{600}{600} + \frac{\text{ns}}{\text{ns}} + \frac{1}{100 \text{ strain}} + 1$		CTADT or Demosted CTADT	Standard Mode		4		μs	
$\begin{tabular}{ c c c c c } \hline \begin{tabular}{ c c c c c } \hline \begin{tabular}{ c c c c c c } \hline \begin{tabular}{ c c c c c c } \hline \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	$t_{HD;STA}$		Fast Mode		600		ns	
$ t_{LOW} = SCL LOW Period = \begin{bmatrix} Fast Mode & 1.3 & \mu \\ High-Speed Mode, C_a \leq 100 pF & 160 & ns \\ High-Speed Mode, C_a \leq 400 pF & 320 & ns \\ High-Speed Mode, C_a \leq 400 pF & 320 & ns \\ ScL HIGH Period & Fast Mode & 4 & \mu \\ Fast Mode & 600 & ns \\ High-Speed Mode, C_a \leq 100 pF & 60 & ns \\ High-Speed Mode, C_a \leq 400 pF & 120 & ns \\ High-Speed Mode, C_a \leq 400 pF & 120 & ns \\ Fast Mode & 4.7 & \mu \\ Fast Mode & 4.7 & \mu \\ Fast Mode & 4.7 & \mu \\ Fast Mode & 600 & ns \\ High-Speed Mode, C_a \leq 400 pF & 120 & ns \\ Fast Mode & 600 & ns \\ High-Speed Mode, C_a \leq 400 pF & 120 & ns \\ Fast Mode & 600 & ns \\ High-Speed Mode & 160 & ns \\ Fast Mode & 100 & ns \\ High-Speed Mode & 100 & ns \\ High-Speed Mode & 100 & ns \\ High-Speed Mode & 0 & 3.45 & \mu \\ Fast Mode & 0 & 900 & ns \\ High-Speed Mode, C_a \leq 100 pF & 0 & 70 & ns \\ High-Speed Mode, C_a \leq 400 pF & 0 & 150 & ns \\ Fast Mode & 20+0.1C_b & 100 \\ High-Speed Mode, C_a \leq 400 pF & 20 & 160 \\ High-Speed Mode, C_a \leq 400 pF & 20 & 160 \\ High-Speed Mode, C_a \leq 400 pF & 20 & 160 \\ High-Speed Mode, C_a \leq 400 pF & 20 & 160 \\ High-Speed Mode, C_a \leq 400 pF & 20 & 160 \\ High-Speed Mode, C_a \leq 400 pF & 10 & 40 \\ High-Speed Mode, C_a $			High-Speed Mode		160		ns	
			Standard Mode		4.7		μs	
$\frac{1}{1} + 160 + $	t	SCL LOW Period	Fast Mode		1.3		μs	
$\begin{tabular}{ c c c c c c } \label{eq:character} $$ SCL HIGH Period $$ $$ SCL HIGH Period $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $$$	LOW	SCL LOW Period	High-Speed Mode, $C_B \leq 100 pF$		160		ns	
$ \begin{tabular}{ c c c c c } \hline Fast Mode & & & & & & & & & & & & & & & & & & &$			High-Speed Mode, $C_B \leqslant 400 pF$		320		ns	
$ \begin{array}{ c c c c c c c } \mbox{SCL HIGH Period} & High-Speed Mode, C_8 \leqslant 100 pF & 60 & ns \\ \hline High-Speed Mode, C_8 \leqslant 100 pF & 120 & ns \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 120 & ns \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 4.7 & \mus \\ \hline Standard Mode & 4.7 & \mus \\ \hline Fast Mode & 600 & ns \\ \hline High-Speed Mode & 160 & ns \\ \hline High-Speed Mode & 160 & ns \\ \hline High-Speed Mode & 160 & ns \\ \hline High-Speed Mode & 100 & ns \\ \hline Fast Mode & 100 & ns \\ \hline High-Speed Mode & 10 & 0 \\ \hline High-Speed Mode & 0 & 3.45 & \mus \\ \hline Fast Mode & 0 & 3.45 & \mus \\ \hline Fast Mode & 0 & 900 & ns \\ \hline High-Speed Mode, C_8 \leqslant 100 pF & 0 & 70 & ns \\ \hline High-Speed Mode, C_8 \leqslant 100 pF & 0 & 150 & ns \\ \hline Fast Mode & 20+0.1C_8 & 300 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 20 & 160 \\ \hline Fast Mode & 20+0.1C_8 & 300 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 400 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 100 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 100 pF & 10 & 80 \\ \hline High-Speed Mode, C_8 \leqslant 100 pF & 10 & 40 \\ \hline \end{array}$			Standard Mode		4		μs	
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$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	LHIGH		High-Speed Mode, $C_B \leq 100 pF$		60		ns	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $			High-Speed Mode, $C_B \leqslant 400 pF$		120		ns	
$\frac{1}{1} + \frac{1}{1} + \frac{1}$			Standard Mode		4.7		μs	
$ \begin{array}{ c c c c c c c c c c } \hline t_{SU;DAT} & Data Setup Time & \hline Standard Mode & 250 & \\ \hline Fast Mode & 100 & \\ \hline High-Speed Mode & 10 & \\ \hline High-Speed Mode & 0 & 3.45 & \mu s \\ \hline Fast Mode & 0 & 900 & ns \\ \hline High-Speed Mode, C_B \leq 100 pF & 0 & 70 & ns \\ \hline High-Speed Mode, C_B \leq 100 pF & 0 & 150 & ns \\ \hline High-Speed Mode, C_B \leq 400 pF & 0 & 150 & ns \\ \hline SCL Rise Time & \hline SCL Rise Time & \hline Standard Mode & 20+0.1C_B & 300 \\ \hline High-Speed Mode, C_B \leq 100 pF & 10 & 80 \\ \hline High-Speed Mode, C_B \leq 100 pF & 10 & 80 \\ \hline High-Speed Mode, C_B \leq 100 pF & 10 & 80 \\ \hline High-Speed Mode, C_B \leq 100 pF & 20 & 160 \\ \hline Fast Mode & 20+0.1C_B & 300 \\ \hline High-Speed Mode, C_B \leq 100 pF & 10 & 80 \\ \hline High-Speed Mode, C_B \leq 100 pF & 10 & 40 \\ \hline \end{array} $	t _{su;sta}	Repeated START Setup Time	Fast Mode		600		ns	
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$\frac{1}{10} + \frac{1}{10} $			Standard Mode		250			
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$ \begin{array}{c c c c c c c c } t_{\text{HD};\text{DAT}} & \text{Data Hold Time} & & & & & & & & & & & & & & & & & & &$			Standard Mode	0		3.45	μs	
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$t_{RCL} SCL \text{ Rise Time} \begin{array}{c c} Standard \text{ Mode} & 20+0.1C_B & 100 \\ \hline Fast \text{ Mode} & 20+0.1C_B & 300 \\ \hline High-Speed \text{ Mode, } C_B \leq 100 \text{pF} & 10 & 80 \\ \hline High-Speed \text{ Mode, } C_B \leq 400 \text{pF} & 20 & 160 \\ \hline High-Speed \text{ Mode, } C_B \leq 400 \text{pF} & 20 & 160 \\ \hline Fast \text{ Mode} & 20+0.1C_B & 300 \\ \hline Fast \text{ Mode} & 20+0.1C_B & 300 \\ \hline Fast \text{ Mode} & 20+0.1C_B & 300 \\ \hline High-Speed \text{ Mode, } C_B \leq 100 \text{pF} & 10 & 40 \\ \hline \end{array} \begin{array}{c} \text{ ns} \end{array}$	LHD;DAT		High-Speed Mode, $C_B \leqslant 100 pF$	0		70	ns	
$t_{\text{RCL}} \begin{array}{c c c c c c } & \text{SCL Rise Time} & \hline Fast Mode & 20+0.1C_B & 300 \\ \hline High-Speed Mode, C_B \leqslant 100 \text{pF} & 10 & 80 \\ \hline High-Speed Mode, C_B \leqslant 400 \text{pF} & 20 & 160 \\ \hline High-Speed Mode, C_B \leqslant 400 \text{pF} & 20 & 160 \\ \hline Fast Mode & 20+0.1C_B & 300 \\ \hline Fast Mode & 20+0.1C_B & 300 \\ \hline High-Speed Mode, C_B \leqslant 100 \text{pF} & 10 & 40 \\ \hline \end{array} \right. \\ \begin{array}{c} \text{rs} \end{array}$			High-Speed Mode, $C_B \leqslant 400 pF$	0		150	ns	
$ \begin{array}{ c c c c c c } t_{RCL} & SCL \mbox{ Rise Time} & High-Speed \mbox{ Mode, } C_B \leqslant 100 \mbox{ PF} & 10 & 80 \\ \hline High-Speed \mbox{ Mode, } C_B \leqslant 400 \mbox{ PF} & 20 & 160 \\ \hline High-Speed \mbox{ Mode, } C_B \leqslant 400 \mbox{ PF} & 20 & 160 \\ \hline \\ Fast \mbox{ Mode} & 20 + 0.1 \mbox{ C}_B & 300 \\ \hline Fast \mbox{ Mode, } C_B \leqslant 100 \mbox{ PF} & 20 & 10 & 10 \\ \hline \\ High-Speed \mbox{ Mode, } C_B \leqslant 100 \mbox{ PF} & 10 & 40 \\ \hline \end{array} \right. \label{eq:result}$			Standard Mode	20+	0.1C _B	100		
$\begin{tabular}{ c c c c c } \hline High-Speed Mode, C_B \leqslant 100 pF & 10 & 80 \\ \hline High-Speed Mode, C_B \leqslant 400 pF & 20 & 160 \\ \hline High-Speed Mode, C_B \leqslant 400 pF & 20+0.1 C_B & 300 \\ \hline Fast Mode & 20+0.1 C_B & 300 \\ \hline High-Speed Mode, C_B \leqslant 100 pF & 10 & 40 \\ \hline \end{tabular}$ ns	t _{RCL}	SCI Pise Time	Fast Mode	20+	0.1C _B	300	ne	
$t_{FCL} SCL Fall Time \begin{array}{c c} Standard Mode & 20+0.1C_B & 300 \\ \hline Fast Mode & 20+0.1C_B & 300 \\ \hline High-Speed Mode, C_B \leqslant 100 pF & 10 & 40 \end{array} \\ \begin{array}{c c} SCL Fall Time & SCL $			High-Speed Mode, $C_B \leq 100 pF$		10	80	115	
$t_{FCL} \qquad SCL \ Fall \ Time \qquad Fast \ Mode \qquad 20+0.1 C_B \qquad 300 \\ High-Speed \ Mode, \ C_B \leqslant 100 pF \qquad 10 \qquad 40 \qquad ns$			High-Speed Mode, $C_B \leq 400 pF$		20	160		
t _{FCL} SCL Fall Time High-Speed Mode, $C_B \leq 100 \text{pF}$ 10 40 ns			Standard Mode	20+	0.1C _B	300		
High-Speed Mode, $C_B \le 100 \text{pF}$ 1040	t		Fast Mode	20+	0.1C _B	300		
High-Speed Mode. C _R ≤400pF 20 80	^L FCL	SCL Fall Time	High-Speed Mode, $C_B \leq 100 pF$		10	40	ns	
			High-Speed Mode, $C_B \leq 400 pF$		20	80		

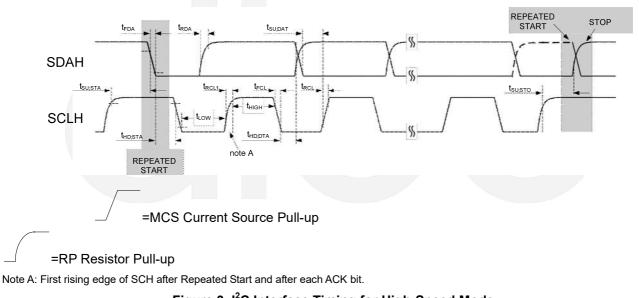


	SDA Rise Time	Standard Mode	20+	0.1C _B	300	
t _{RDA}	Rise Time of SCL after a	Fast Mode	20+	0.1C _B	300	
t _{RCL1}	Repeated START Condition and	High-Speed Mode, $C_B \leqslant 100 pF$		10	80	ns
	after ACK Bit	High-Speed Mode, $C_B \leq 400 pF$		20	160	
		Standard Mode	20+	0.1C _B	300	
tena SDA Fall Time	Fast Mode	20+0.1C _B		300		
t _{FDA}		High-Speed Mode, $C_B \leq 100 pF$		10	80	ns
		High-Speed Mode, $C_B \leq 400 pF$		20	160	
		Standard Mode		4		μs
t _{su;sто}	Stop Condition Setup Time	Fast Mode		600		ns
		High-Speed Mode		160		ns
C _B	Capacitive Load for SDA, SCL				400	рF
1						

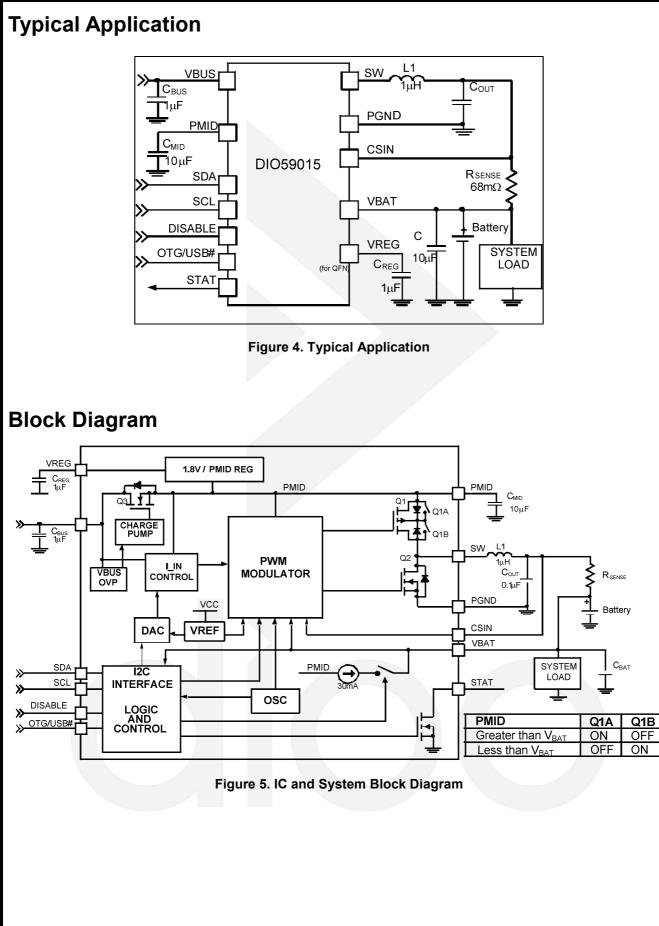
Timing Diagrams







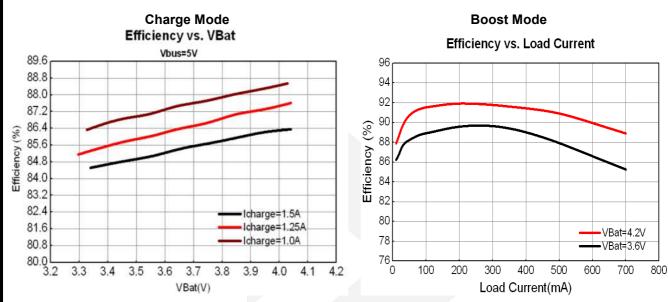






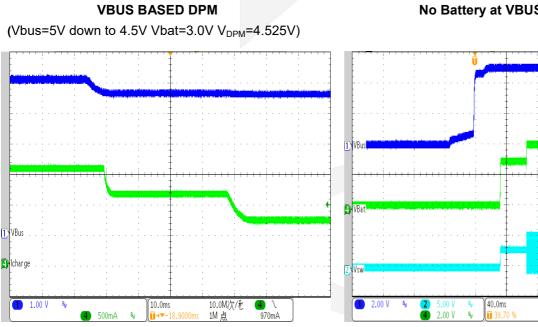
Typical Performance Characteristic

Typical value: T_A = 25°C, V_{IN}=5V, unless otherwise specified.



Charge Mode Typical Characteristics

Unless otherwise specified, V_{OREG}=4.2V, V_{BUS}=5.0V, and T_A=25°C.



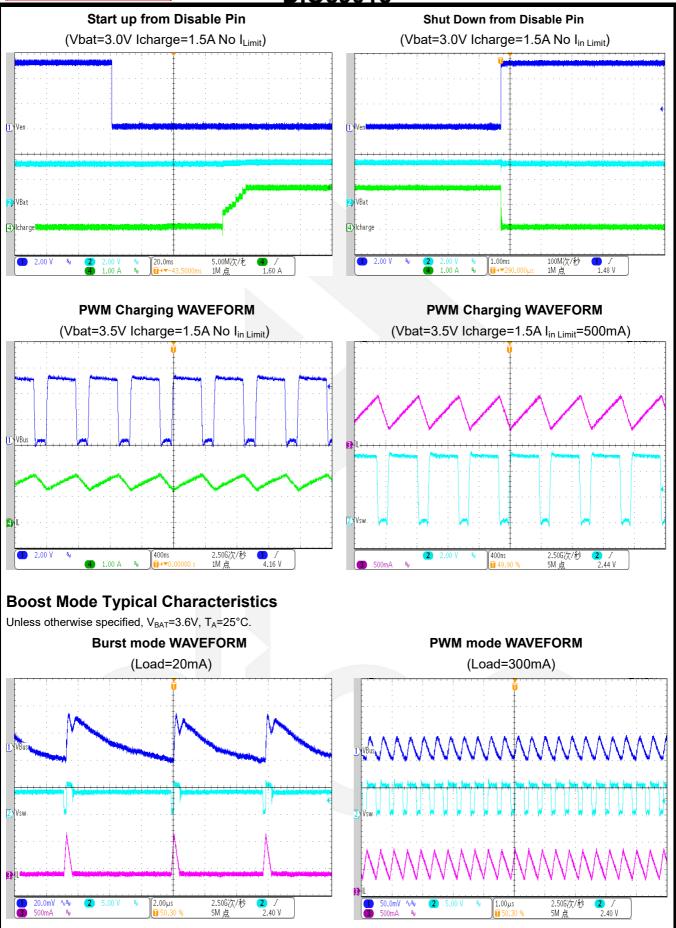
No Battery at VBUS Power-up

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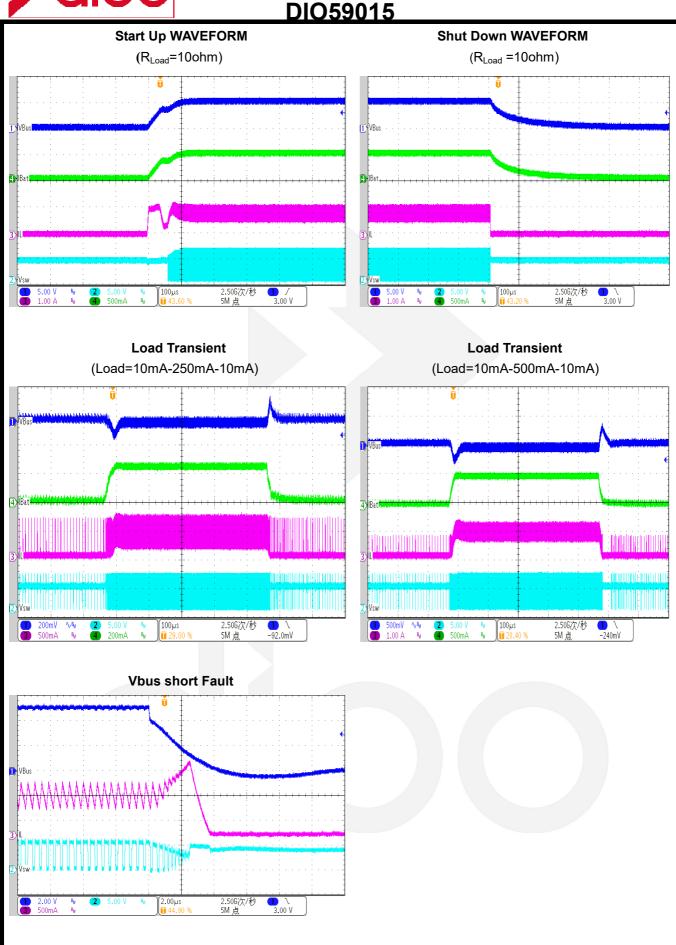
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USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator







Application Information

Circuit Description/Overview

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

DIO59015 combines a highly integrated synchronous buck regulator for charging with a synchronous boost regulator, which can supply 5V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

The DIO59015 has three operating modes:

- 1. Charge Mode:
- Charge a signal-cell Li-ion or Li-polymer battery.
- 2. Boost Mode:

Provides 5V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.

3. High-Impedance Mode:

Both the boost and charging circuits are OFF in this mode. Current flow from VBUS to the battery or from the battery to VBUS is blocked in this mode. This mode consumers very little current from VBUS or the battery.

Charge Mode

In charge Mode, DIO59015 employs four regulation loops:

- 1. Input Current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I²C interface.
- 2. Charging Current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.
- 3. Charge Voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage roses, the battery's internal impedance and R_{SENSE} work in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the voltage across R_{SENSE} drops below the I_{TERM} threshold.
- 4. Temperature: If the IC's junction temperature reaches 120℃,charge current is reduced until the IC's temperature stabilizes at 120℃.
- 5. An additional loop limits the amount of drop on VBUS to a programmable voltage (V_{SP}) to accommodate "special chargers" that limit current to a lower current than might be available from a "normal" USB wall charger.

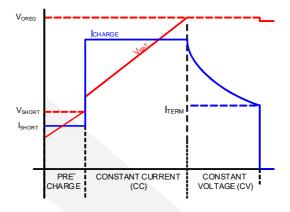
Battery Charging Curve

If the battery voltage is below V_{SHORT} , a linear current source pre-charges the battery until V_{BAT} reaches V_{SHORT} . The PWM charging circuit is then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The DIO59015 is designed to work with a current-limited input source at VBUS. During the current regulation phase of charging, I_{INLIM} or the programmed charging current limits the current available to charge the battery and



power the system. The effect of I_{INLIM} on I_{CHARGE} can be see in Figure 7.





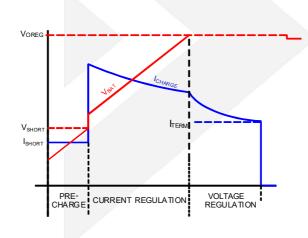


Figure 7. Charge Curve, IINLIM Limits ICHARGE

Assuming that V_{OREG} is programmed to the cell's fully charged "float" voltage, the current that the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to V_{OREG} declines, and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting he TE bit (REG[3]).

The charger output or "float" voltage can be programmed by the OREG bits from 4.2V to 4.44V in 20mV increments, as shown in Table 1.

Decimal	Hex	VOREG
0~35	00~23	4.20
36~40	24~28	4.30
41~43	29~2B	4.35
44~62	2C~3E	4.40

The following charging parameters can be programmed by the host through I^2C .

USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator



Table 2. Programmable Charging Parameters

Parameter	Name	Register
Output Voltage Regulation	V _{OREG}	REG2[7:2]
Battery Charging Current Limit	I _{OCHRG}	REG4[6:4]
Input Current Limit	I _{INLIM}	REG1[7:6]
Charge Termination Limit	I _{TERM}	REG4[2:0]

A new charge cycle begins when one of the following occurs:

- The battery voltage falls below V_{OREG}-V_{RCH}
- VBUS Power on Reset (POR) clears and the battery voltage is below the V_{SHORT}.
- CE or HZ_MODE is rest through I²C write to CONTROL1 (Reg1) register.

Charge Current Limit (I_{OCHARGE})

Table 3. I_{OCHARGE} (REG4 [6:4]) Current as Function of I_{OCHARGE} Bits and R_{SENSE} Resistor Values

DEC	DEC BIN HEX		VRSENSE	I _{OCHARGE} (mA)	
DEC	DIN			68mΩ	100mΩ
0	000	00	37.5	551	375
1	001	01	44.4	653	444
2	010	02	51.2	753	512
3	011	03	57.5	846	575
4	100	04	71.3	1048	713
5	101	05	78.1	1149	781
6	110	06	91.9	1351	919
7	111	07	101.8	1498	1018

Table 4. V_{RCH} (REG7 [1:0]) Recharge Voltage

DEC	BIN	HEX	V _{RCH} (mV)
0	00	00	50
1	01	01	100
2	10	02	150
3	11	03	200

Termination Current Limit

Current charge termination is enabled when TE (REG1[3])=1. Typical termination current values are given in Table 5.



Table 5. I_{TERM} Current as Function of I_{TERM} Bits (REG4[2:0]) and R_{SENSE} Resistor Values

L			(mA)	
I _{TERM}	(mV)	68mΩ	100mΩ	
0	3.1	46	31	
1	6.3	92	63	
2	9.4	138	94	
3	12.5	184	125	
4	15.6	230	156	
5	18.8	276	188	
6	21.9	322	219	
7	25	368	250	

When the charge current falls below I_{TERM}, PWM charging stops and the STAT bits change to READY (00) for about 30ms while the IC determines whether the battery and charging source are still connected. STAT then changes to CHARGE DONE (10), provided the battery and charger are still connected.

PWM Controller in Charge Mode

The IC uses a current-mode PWM controller to regulator the output voltage and battery charge currents. The synchronous rectifier (Q2) has a current limit that which off the FET when the current is negative by more than 300mA peak. This prevents current flow from battery.

V_{BUS} POR/Non-Compliant Charger Rejection

When the IC detects that VBUS has risen above $V_{IN(MIN)}$ (4.3V), the IC applies a 250 Ω load from VBUS to GND. To clear the VBUS POR (Power-On-Reset) and begin charging, VBUS must remain above $V_{IN(MIN)}$ and below VBUS_{OVP} for t_{VBUS_VALID} (30ms) before the IC initiates Charging. The VBUS validation sequence always occurs charging is initiated or re-initiated (for example, after a VBUS OVP fault or a V_{RCH} recharge initiation). t_{VBUS_VALID} ensures that unfiltered 50/60Hz chargers and other non-compliant chargers are rejected.

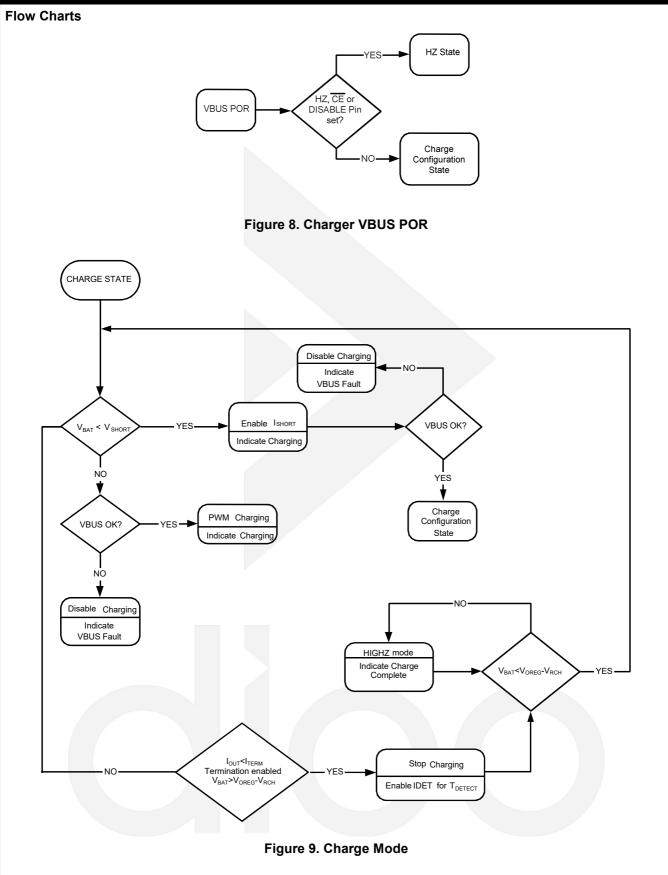
Input Current Limiting

To minimize charging time without overloading VBUS current limitations, the IC's input current limit can be programmed by the I_{INLIM} bits (REG1[7:6]).

IINLIM REG[7:6]	Input Current Limit	
00	100 mA	
01	500 mA	
10	800 mA	
11	No limit	

Table 6. Input Current Limit





Special Charger

The DIO59015 has additional functionality to limit input current in case a current-limited "special charger" is supplying VBUS. These slowly increase the charging current until either.

18

■ I_{INLIM} or I_{OCHARGE} is reached

USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

■ V_{BUS}=V_{SP}.

If V_{BUS} collapses to V_{SP} when the current is ramping up, the DIO59015 charge with an input current that keeps $V_{BUS}=V_{SP}$. When the V_{SP} control loop is limiting the charge current, the SP bit (REG5[4]) is set.

:			
DEC	BIN	HEX	V _{SP}
0	000	00	4.225
1	001	01	4.300
2	010	02	4.375
3	011	03	4.450
4	100	04	4.525
5	101	05	4.600
6	110	06	4.675
7	111	07	4.750

Table 7. V_{SP} as Function of SP Bits (REG5[2:0])

Thermal Regulation and Protection

When the IC's junction temperature reaches T_{CF} (about 120°C), the charger reduces its output current to 550mA to prevent overheating. If the temperature increases beyond $T_{SHUTDOWN}$; charging is suspended, the FAULT bits are set to 101, and STAT is pulsed HIGH. In Suspend Mode, all timers stop and the state of the IC's logic is preserved. Charging resumes at programmed current after the die cools to about 120°C.

Additional θ_{JA} data points, measured using the DIO59015 evaluation board, are given in Table 8 (measured with TA=25°C). Note that as power dissipation increases, the effective θ_{JA} decreases due to the larger difference between the die temperature and ambient.

Power (W)	θ _{JA}
0.504	54°C/W
0.844	50°C/W
1.506	46°C/W

Table 8. Evaluation Board Measured θ_{JA}

Charge Mode Input Supply Protection

Sleep Mode

When V_{BUS} falls below $V_{BAT}+V_{SLP}$, and V_{BUS} is above $V_{IN(MIN)}$. the IC enters Sleep Mode to prevent the battery from draining into VBUS. During Sleep Mode, reverse current is disabled by body switching Q1.

Input Supply Low-Voltage Detection

The IC continuously monitors VBUS during charging. If V_{BUS} falls below $V_{\text{IN(MIN)}},$ the IC:

- 1. Terminates charging.
- 2. Pulses the STAT pin, sets the STAT bits to 11, and sets the FAULT bits to 011.

If V_{BUS} recovers above the $V_{IN(MIN)}$ rising threshold after time t_{INT} (about two seconds), the charging process is repeated. This function prevents the USB power bus from collapsing or oscillating when the IC is connected to a suspended USB port or a low-current-capable OTG device.

Input Over-Voltage Detection

When the V_{BUS} exceeds VBUS_{OVP}, the IC:



1. Turns off Q3

2. Suspends charging

3. Sets the FAULT bits to 001, sets the STAT bits to 11, and pulses the STAT pin.

When V_{BUS} falls about 150mV below VBUS_{OVP}, the fault is cleared and charging resumes after V_{BUS} is revalidated (see VBUS POR/Non-Compliant Charger Rejection).

VBUS Short While Charging

If VBUS is shorted with a very low impedance while the IC is charging with II_{NLIMIT} =100mA, the IC may not meet datasheet specifications until power is removed. To trigger this condition, V_{BUS} must be driven from 5V to GND with a high slew rate. Achieving this slew rate requires a 0 Ω short to the USB cable less than 10cm from the connector.

Charge Mode Battery Detection & Protection VBAT Over-Voltage Protection

The OREG voltage regulation loop prevents V_{BAT} from overshooting the OREG voltage when the battery is removed. When the PWM charger runs with no battery, the TE bit is not set and a battery is inserted that is charged to a voltage higher than V_{OREG} ; PWM pulses stop. If no further pulses occur for 30ms, the IC sets the FAULT bits to 100, sets the STAT bits to 11, and pulses the STAT pin.

Battery Detection During Charging

The IC can detect the presence, absence. During normal charging, once VBAT is close to VOREG and the termination charging, once VBAT is close to VOREG and the termination charge current is detected, the IC terminates charging and sets the STAT bits to 10. It then turns on a discharge current, I_{DETECT}, for t_{DETECT}. If VBAT is still above 2V, the battery is present and the IC sets the FAULT bits to 000. If VBAT is below 2V, the battery is absent and the IC sets the FAULT bits to 000. If VBAT is below 2V, the battery is

- 1. Operation with No Battery
- 2. Sets the FAULT bits to 111.

Battery Short-Circuit Protection

If the battery voltage is below the short-circuit threshold (V_{SHORT}); a linear current source, I_{SHORT} , supplies V_{BAT} until V_{BAT} > V_{SHORT} .

System Operation with No Battery

The DIO59015 continues charging after VBUS POR with the default parameters, regulating the V_{BAT} line to 3.78V (if set V_{OREG} at 4.2V). In this way, the DIO59015 can start the system without a battery. Re-connect power to VBUS or reset ENN pin, IC can exit No Battery Mode.

Charger Status/Fault Status

The STAT pin indicates the operating condition of the IC and provides a fault indicator for interrupt driven systems.

EN_STAT	EN_STAT Charge State			
X	No Charging	OPEN		
1	Charging	LOW		
x	Fault	2Hz Pulse		

Table 9. STAT Pin Function



The FAULT bits (Reg0[2:0]) indicate the type of fault in Charge Mode (see Table 10).

Table 10. Fault Status Bits During Charge Mode

I	Fault Bit		Fault Description
B2	B1	B0	Fault Description
0	0	0	Normal (No Fault)
0	0	1	VBUS OVP
0	1	0	Sleep Mode
0	1	1	Poor Input Source
1	0	0	Battery OVP
1	0	1	Thermal Shutdown
1	1	0	N.A
1	1	1	No Battery

Charge Mode Control Bits

Setting either HZ_MODE or \overline{CE} through I²C disables the charger and puts the IC into High-Impedance Mode.

Charging	DISABLE Pin	CE	HZ_MODE
ENABLE	0	0	0
DISABLE	х	1	Х
DISABLE	х	Х	1
DISABLE	1	X	Х

Table 11. DISABLE Pin and CE Bit Functionality

Operational Mode Control

OPA_MODE (REG1[0]) and the HZ_MODE (REG1[1]) bits in conjunction with the FAULT state define the operational mode of the charger. Before VBUS connected to power source, IC should enter charge mode.

HZ_MODE	OPA_MODE	FAULT	Operation Mode		
0	0	0	Charge		
0	х	1	No charging		
0	1	0	Boost		
1	×	Х	High Impedance		

Table 12. Operation Mode Control

Boost Mode

Boost Mode can be enabled if OTG pin and OPA_MODE bits as indicated in Table 13. The OTG pin ACTIVE state is 1 if OTG_PL=1 and 0 when OTG_PL=0.

If boost is active using the OTG pin, Boost Mode is initiated even if the HZ_MODE=1. The HZ_MODE bit overrides the OPA_MODE bit.

	Tuble		BOOSt	
OTG_EN	OTG Pin	HZ_MODE	OPA_MODE	BOOST
1	ACTIVE	Х	Х	Enabled
Х	Х	0	1	Enabled
Х	ACTIVE	Х	0	Disabled
0	Х	1	Х	Disabled
1	ACTIVE	1	1	Disabled
0	ACTIVE	0	0	Disabled

Table 13. Enabling Boost



Boost COT Control

The IC uses a constant on-time and valley current detect to regulate VBUS. The regulator achieves excellent transient response by employing current-mode modulation. This technique causes the regulator to exhibit a load line. During COT Mode, the output voltage drops slightly as the input current rises. With a constant V_{BAT} , this appears as a constant output resistance.

The "droop" caused by the output resistance when a load is applied allows the regulator to respond smoothly to load transient with no undershoot from the load line. This can be seen in and Figure 10

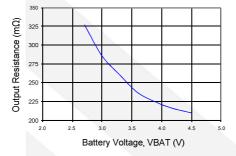


Figure 10. Output Resistance (ROUT)

V_{BUS} as a function of I_{LOAD} can be computed when the regulator is in	PWM Mode (continuous conduction) as:
V _{OUT} =5.15-R _{OUT} ·I _{LOAD}	EQ.1
At V_{BAT} =3.3V, and I_{LOAD} =200mA, V_{BUS} would drop to:	
V _{OUT} =5.15-0.26·0.2=5.098V	EQ.1A
At Var=2.7V and Lar=200mA. Vara would drop to:	

At V_{BAT} =2.7V, and I_{LOAD} =200mA, V_{BUS} would drop to:

V_{OUT}=5.15-0.327·0.2=5.085V EQ.1B

PFM Mode

If VBUS>VREF_{BOOST} (nominally 5.07V) when the valley current comes to 0, the regulator enters PFM Mode. Boost pulses are inhibited until V_{BUS} <VREF_{BOOST}. Once V_{BUS} <VREF_{BOOST}, boost pulses are allowed for one or several times until V_{BUS} >VREF_{BOOST}. Therefore the regulator behaves like a burst mode regulator, with the average of its output voltage ripple at 5.07V in PFM Mode.

	_	-
Mode	Description	Invoked When
LIN	Linear Startup	V _{BAT} >V _{BUS}
SS	Boost Soft-Start	V _{BUS} <v<sub>BST</v<sub>
BST	Peast Operation Made	V _{BAT} >UVLO _{BST} and SS
851	Boost Operation Mode	Completed

Table 14. Boost PWM Operating States

Startup

When the boost regulator is shut down, current flow is prevented from V_{BAT} to V_{BUS} , as well as reverse flow from V_{BUS} to V_{BAT} .

LIN State

When EN rises, if V_{BAT} >UVLO_{BST}, the regulator attempts to bring PMID within 200mV of VBAT using an internal 450mA current source from VBAT (LIN State). If PMID has not achieved V_{BAT} - 200mV after 500µs, a FAULT state



is initiated.

SS State

When PMID>V_{BAT}-200mV, the boost regulator begins switching with a SS modulator. The output slews up slowly and smoothly until V_{BUS} =VREF_{BOOST}.

If the output fails to achieve set point (VBST) within SS time, normally 128 μ s, a fault state is initiated.

BST State

This is the normal operating mode of the regulator. The regulator uses a constant on-time and valley current detect modulation scheme. The minimum t_{ON} is proportional to $\frac{V_{OUT} - V_{IN}}{V_{OUT}}$, which keeps the regulator's switching

frequency reasonably constant in CCM.

To ensure the VBUS does not pump significantly above the regulation point, the boost switch remains off as long as $FB>V_{REF}$.

Boost Faults

If a Boost FAULT OCCURS:

- 1. OPA_MODE bit is reset.
- 2. The power stage is in High-Impedance Mode.
- 3. The FAULT bits (REG0[2:0]) are set per Table 15.

Restart After Boost Faults

If boost was enabled with the OPA_MODE bit and OTG_EN=0, Boost Mode can only be enabled through subsequent I²C commands since OPA_MODE is reset on boost faults. If OTG_EN=1 and the OTG pin is still ACTIVE (see Table 13), the boost restarts after a 5.2ms delay, as shown in Figure 11. If the fault condition persists, restart is attempted every 10ms until the fault clears or an I²C command disables the boost.

			-
F	Fault Bit		Foult Depariation
B2	B1	B0	Fault Description
0	0	0	Normal (no fault)
 0	0	1	V _{BUS} >VBUS _{OVP}
0	1	0	VBUS fails to achieve the voltage required to advance to the next state during soft-start or sustained (>50µs) current limit during the BST state.
0	1	1	N/A: This code does not appear.
 1	0	0	N/A: This code does not appear.
1	0	1	Thermal shutdown
1	1	0	N/A: This code does not appear.
1	1	1	N/A: This code does not appear.

Table 15. Fault Bits During Boost Mode



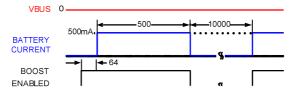


Figure 11. Boost Response Attempting to Start into VBUS Short Circuit (Times in µs)

VREG Pin

The 1.8V regulated output on this pin can be disabled through I²C by setting the DIS_VREG bit (REG5[6]). VREG can supply up to 2mA. This circuit, which is powered from PMID, is enabled only when PMID>VBAT and does not drain current from the battery. During boost, VREG is off. It is also off when the HZ_MODE bit (REG1[1])=1.

Monitor Register (Reg10H)

Additional status monitoring bits enable the host processor to have more visibility into the status of the IC. The monitor bits are real-time status indicators.

I²C Interface

The DIO59015's serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Mode I2C-Busspecifications.TheSCLlineisaninputandtheSDAlineisabi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and signaling ACK. All data is shifted in MSB (bit 7) first.

Slave Address

Table 16. I²C Slave Address Byte

Part Type	7	6	5	4	3	2	1	0
DIO59015	1	1	0	1	0	1	0	R/W

In hex notation, the slave address assumes a 0LSB. The hex slave address for the DIO59015 is D4H and is D6H for all other parts in the family.

Bus Timing

As shown in Figure 12, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

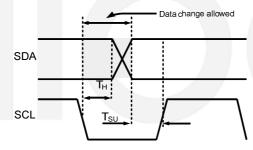


Figure 12. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCLHIGH.A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCLHIGH, as shown in Figure 13.



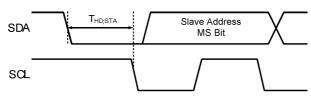


Figure 13. Start Bit

A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 14.

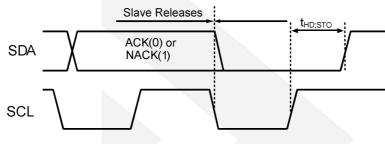


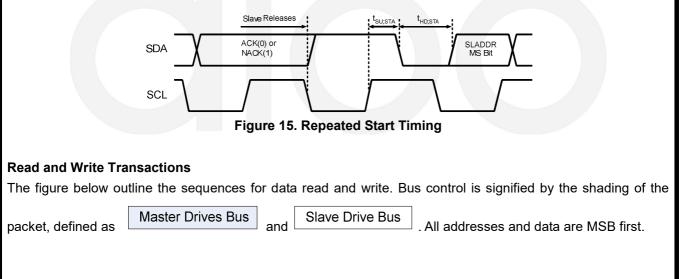
Figure 14. Stop Bit

During a read from theDIO59015(Figure 16,Figure 17), the master issues a Repeated Start after sending the register address and before resending the slave address. The Repeated Start is a 1-to-0transition on SDA while SCL is HIGH, as shown in Figure 15.

High-Speed (HS) Mode

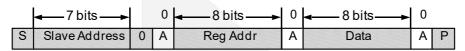
The protocols for High-Speed(HS), Low-Speed(LS), and Fast-Speed(FS) Modes are identical except the bus speed for HS Mode is 3.4MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a start condition. The master code is sent in Fast or Fast Plus Mode (less than1MHz clock); slaves do not ACK this transmission.

The master then generates a repeated start condition (Figure 15) that causes all slaves on the bus to switch to HS Mode. The master then sends I²C packets, as described above, using the HS Mode clock rate and timing. The bus remains in HS Mode until a stop bit (Figure14) is sent by the master. While in HS Mode, packets are separated by repeated start conditions (Figure 15).



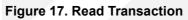


Tabl	Table 17. Bit Definitions for Figure 16, Figure 17										
Symbol	Definition										
S	START, see Figure 13										
А	ACK. The slave drives SDA to 0 to acknowledge the										
	preceding packet.										
Ā	NACK. The slave sends a 1 to NACK the preceding packet.										
R	Repeated START, see Figure 15										
Р	STOP, see Figure 14.										









Register Bit Definitions

1 CONTROL0 Register (0x00) Default Value=X1XX0XXX

<u>1 CC</u>	DNTRC	DL0 Register	r (0x00) Default Value=X1X	XUXXX			1	1	1	
Bit		Bit 7	Bit 6	Bit	Bit	Bit 3	Bit 2	Bit 1	Bit 0	
NA	ME	Reserved	EN_STAT	ST	AT	BOOST		FAULT	'	
R/V	V	R/W	R/W	F	ł	R		R		
		Unused	0:	00 : C	narge	0:	for Charge Mod	e:		
			Prevents STAT pin from	Ready		Boost does	000 = Normal (I	No Fault)		
			going LOW during charging;	01 : Charge		not operate	001 = VBUS OVP			
			STAT pin still pulses to							
			enunciate faults	10 : C	narge	operates	011 = Poor Input Source 100 = Battery OVP			
			1 : Enables STAT pin LOW	done			100 = Battery OVP			
	when IC is charging.				ault		101 = Thermal Shutdown			
							110 = N.A			
							111 = No Batter			
							for Boost Mode			
Fur	nction						000 = Normal (I	no fault)		
							001 = VBUS>V	BUS _{OVP}		
							010 = VBUS fai	Is to achieve the	voltage required	
							to advance to the	ne next state durin	ng soft-start or	
							sustained (>50	us) current limit di	uring the BST	
							state.			
							011 = VBAT <uvlobst< td=""></uvlobst<>			
							100 = N/A: This	code does not a	ppear.	
							101 = Thermal shutdown			
								code does not a		
							111 = N/A: This	code does not a	ppear.	
L							1			



2 CONTRO	0L1 Regis	ter (0x	01) 🛛	efault	Value=0111 0000 (70h)			
Bit	Bit 7 Bit 6 Bit 5 Bit 4			Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	I _{INLIM} Reserved				ТЕ	CE	HZ_MODE	OPA_MODE
R/W	R/W R/W				R/W	R/W	R/W	R/W
	Input current		Unused		0 :Disable charge current	0 :Charger	0:Not High-Impedance	0 :Charge
	limit:				termination.	enabled.	Mode.	Mode.
Function	00:100 mA				1 : Enable charge current	1 : Charger	1 : High-Impedance	1:Boost Mode.
FUNCTION	01 :500 mA				termination.	disabled.	Mode.	
	10 :800 r	10 :800 mA						
	11: No lii	nit						

3 OREG Register (0x02) Default Value=0000 1010 (0Ah)

	gioto: (one				(****)			
Bit	Bit 7 Bit 6 Bit 5		Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
NAME		I	OF	EG	OTG_PL	OTG_EN		
R/W			R	W	R/W	R/W		
	Charger o	output "float"	voltage;		0 :OTG pin active LOW.	0:		
Function	programm	hable from 4	.2 to 4.4V;	defaults to (1 : OTG pin active HIGH.	Disables OTG pin.		
Function	00 0000~	10 0011 : 4.	2V; 10 0	100~10 100		1 : Enables OTG pin.		
	10 1001~1	10 1011: 4.3	85V; 10 1	100~11 11				

4 IC_INFO Register (0x03) Default Value=1001 0100 (94h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1 Bit 0			
NAME	F	Reserved			PI	N	REV			
R/W				R		R				
Function	Identifies the I	C supplier.		Part nun	nber bits.		IC Revision, revision decimal of these three	1.X, where X is the bits.		

5 IBAT Register (0x04) Default Value=1000 1001 (89h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
NAME	Reserved		V(I _{OCHARGE})		Reserved	V(I _{TERM})				
R/W	R/W		R/W		R/W		R/W			
	0 =	Programs the m	aximum charge o	current	Unused	Sets the curren	t used for chargi	ng termination		
	Unused	000: 37.5mV;	001: 44.4mV;			000 : 3.1mV;	001: 6.3mV;			
		010: 51.2 mV;	011: 57.5 mV;			010: 9.4mV;	011: 12.5mV;			
Function		100: 71.3 mV;	101: 78.1 mV;			100: 15.6mV;	101: 18.8mV;			
FUNCTION		110: 91.9 mV;	111: 101.8 m\	/;		110: 21.9mV;	111: 25mV;			
		The charge curre	nt step (I _{OCHARGE})	is calculated		The termination current step (I _{TERM}) can				
		using:				calculated using:				
		I _{OCHARGE} = V(I _C	DCHARGE)/RSENSE;			I _{TERM} = V(I _{TERM})/ R _{SENSE} ;				



6 SP_CHA	RGER Reg	ister (0x05) Defa	ult Value=0	X1X X100				
Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	Reserve	DIS_VREG	Reserve	SP	EN_LEVEL		VSP	1
R/W	R/W	R/W	R/W	R	R		R/W	
	Unused	0 :1.8V regulator is	Unused	0 :Special charger is not	0 : DISABLE pin	Special ch	arger inpu	ıt
		ON.		active (V_{BUS} is able to stay	is LOW .	regulation voltage		
		1 : 1.8V regulator		above V_{SP}).	1 : DISABLE pin	000: 4.225V; 001: 4.300V;		
Function		is OFF.		1 : Special charger has	is HIGH.	010: 4.375	5V; 011: 4.	450V;
		DFN-12: Default=1		been detected and $V_{\mbox{\scriptsize BUS}}$ is		100: 4.525	5V; 101: 4.	600V;
		QFN-16: Default=0		being regulated to V_{SP} .		110: 4.675	5V; 111: 4.	750V

7 Register (0x07) Default Value=0000 0001 (01h)

Bit	Bit 7	Bit 6	Bit 5		Bit 4		Bit 3	Bit 2	Bit 1	Bit 0		
NAME		Reserved			Reserved Reserved			rved	V _{RCH}			
R/W	R/W			R/W			R/	W	R/W			
		Unused			Unused	1	Unu	sed	Recharge voltag	Recharge voltage of V _{OREG} drops.		
Function									00: 50mV; 0 ²	l: 100mV;		
									10: 150mV; 11: 200mV			

8 MONITOR Register (0x10h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
NAME	ITERM_CMP	V _{BAT_CMP}	LINCHG	T_120	I _{CHG}	I _{BUS}	VBUS_VALID	сv			
R/W	R	R	R	R	R	R	R	R			
Function	I _{term_cmp:}										
	ITERM comparator output. 0: V _{CSIN} -V _{BAT} >V _{ITERM.} 1 : V _{CSIN} -V _{BAT} <v<sub>ITERM</v<sub>										
	V _{BAT_CMP}										
	Output of VBAT comparator in charging mode, 0: V_{BAT} $< V_{SHORT}$ 1 : V_{BAT} $> V_{SHORT}$										
	LINCHG										
	In charging mode ,0: 30mA linear charger Not Enable; 1: 30mA linear charger Enable.										
	T_120										
	Thermal regulat	tion comparator C	: T _J <120°C; 1: T _J :	>120°C							
	I _{CHG}										
	In charging mode	e, 0: Charging Curr	ent Controlled by I	CHARGE Control L	.oop .1 : Ch	narging Curre	ent Not Controlled by	/ I _{CHARGE}			
	Control Loop.										
	I _{BUS}										
	In charging mode	e,0: I _{BUS} Limiting Cl	narging Current. 1:	Charge Curren	t Not Limited	by I_{BUS}					
	$V_{\text{BUS}_\text{VALID}}$										
	When V_{BUS} > V_{BAT} ,0: V_{BUS} Not Valid 1: V_{BUS} is Valid										
	cv										
	In charging mod	le. 0:Constant Curr	ent Charging. 1:0	Constant Voltage	e Charging.						
Note: Re	gister (0x10h) is fo	or Charge mode or	ıly.								
L											

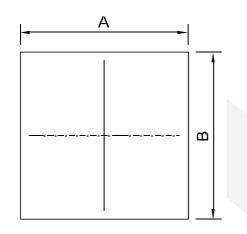


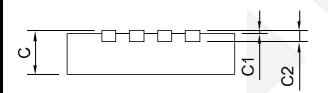
PCB Layout Recommendations

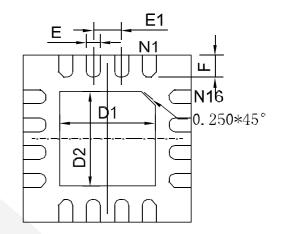
Bypass capacitors should be placed as close to the IC as possible. In particular, the total loop length for CMID should be minimized to reduce overshoot and ringing on the SW, PMID, and VBUS pins. All power and ground pins must be routed to their bypass capacitors, using top copper whenever possible. Copper area connecting to the IC should be maximized to improve thermal performance if possible.



Physical Dimensions: TQFN3*3-16

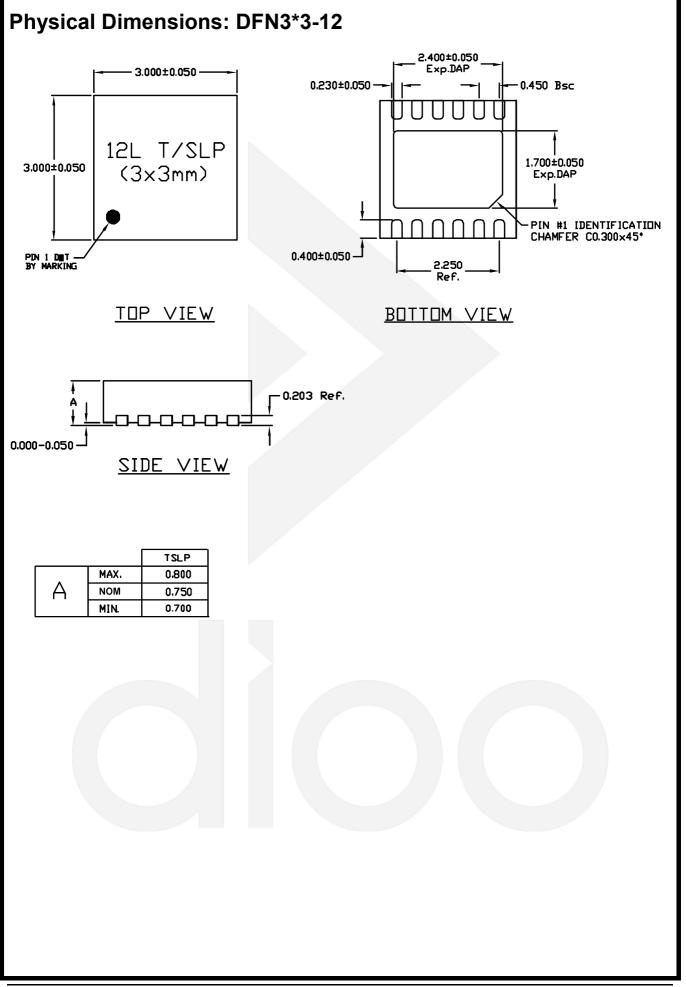






COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)			
Symbol	MIN	NOM	MAX
А	2.9	3.0	3.1
В	2.9	3.0	3.1
С	0.70	0.75	0.80
C1	0	0.025	0.05
C2	0.203TYP		
D1	1.70 TYP		
D2	1.70TYP		
E	0.25TYP		
E1	0.50TYP		
F	0.40TYP		







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